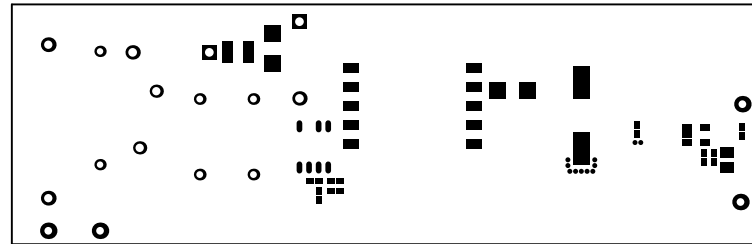
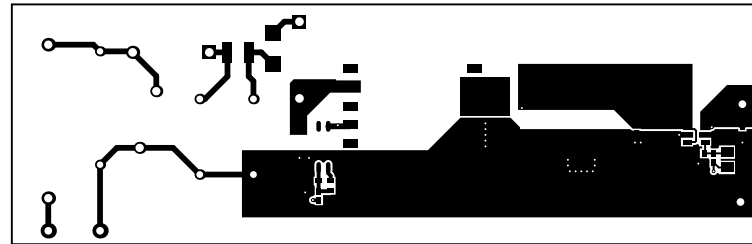


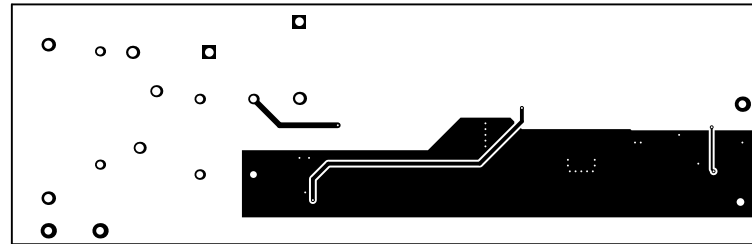
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20457	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 12/8/2016 4:50:18 PM	TEXAS INSTRUMENTS	



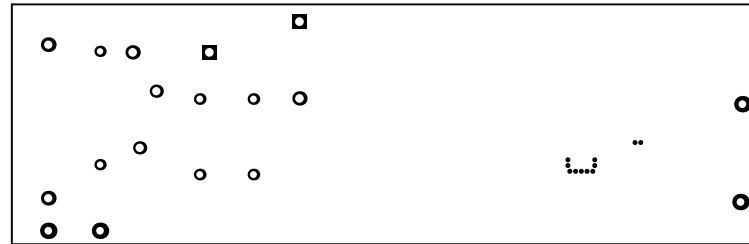
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20457	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 12/8/2016 4:50:18 PM	TEXAS INSTRUMENTS	



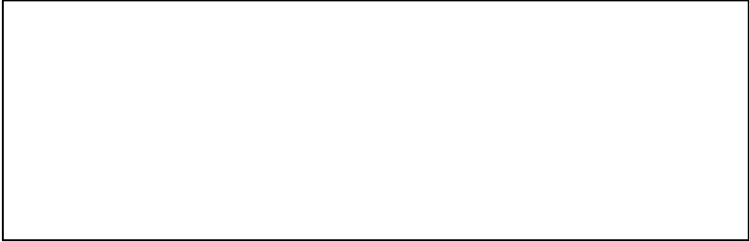
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20457	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 12/8/2016 4:50:18 PM	TEXAS INSTRUMENTS	



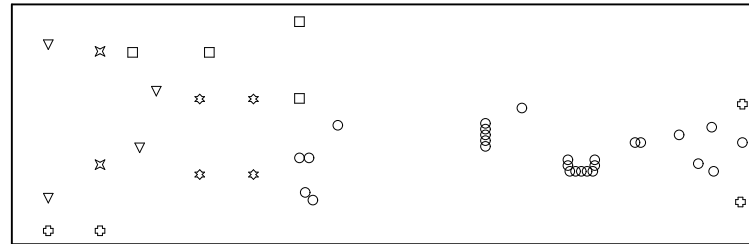
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20457	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 12/8/2016 4:50:19 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20457	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/8/2016 4:50:19 PM	TEXAS INSTRUMENTS	

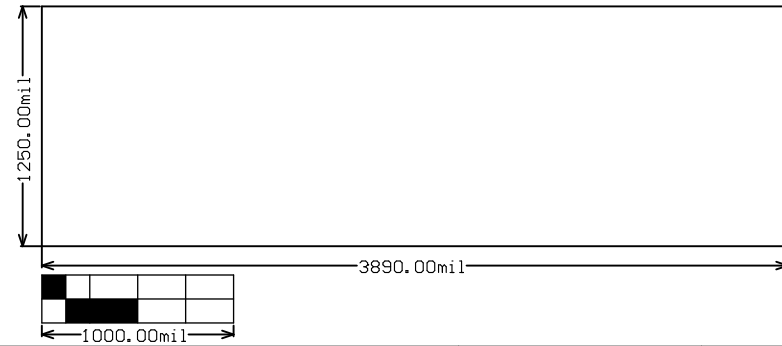


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20457	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 12/8/2016 4:50:20 PM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	27	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	4	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
⊚	4	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
	45 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20457	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 12/8/2016 4:50:20 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20457	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 12/8/2016 4:50:21 PM	TEXAS INSTRUMENTS	

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